

SOT1404-3

wafer level chip-scale package; 36 bumps; 2.07 mm x 2.07 mm x 0.42 mm body

18 October 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP36
Package type industry code	WLCSP36
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	26-4-2016
Manufacturer package code	SOT1404-3

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.04	-	2.07	2.1	mm
E	package width	2.04	-	2.07	2.1	mm
A	seated height	0.39	-	0.42	0.45	mm
A ₂	package height	0.265	-	0.29	0.315	mm
e	nominal pitch	-	-	0.35	-	mm
n ₂	actual quantity of termination	-	-	36	-	A/A



2. Package outline

WLCSP36: wafer level chip-scale package; 36 bumps; 2.07 x 2.07 x 0.42 mm (backside coating included) SOT1404-3

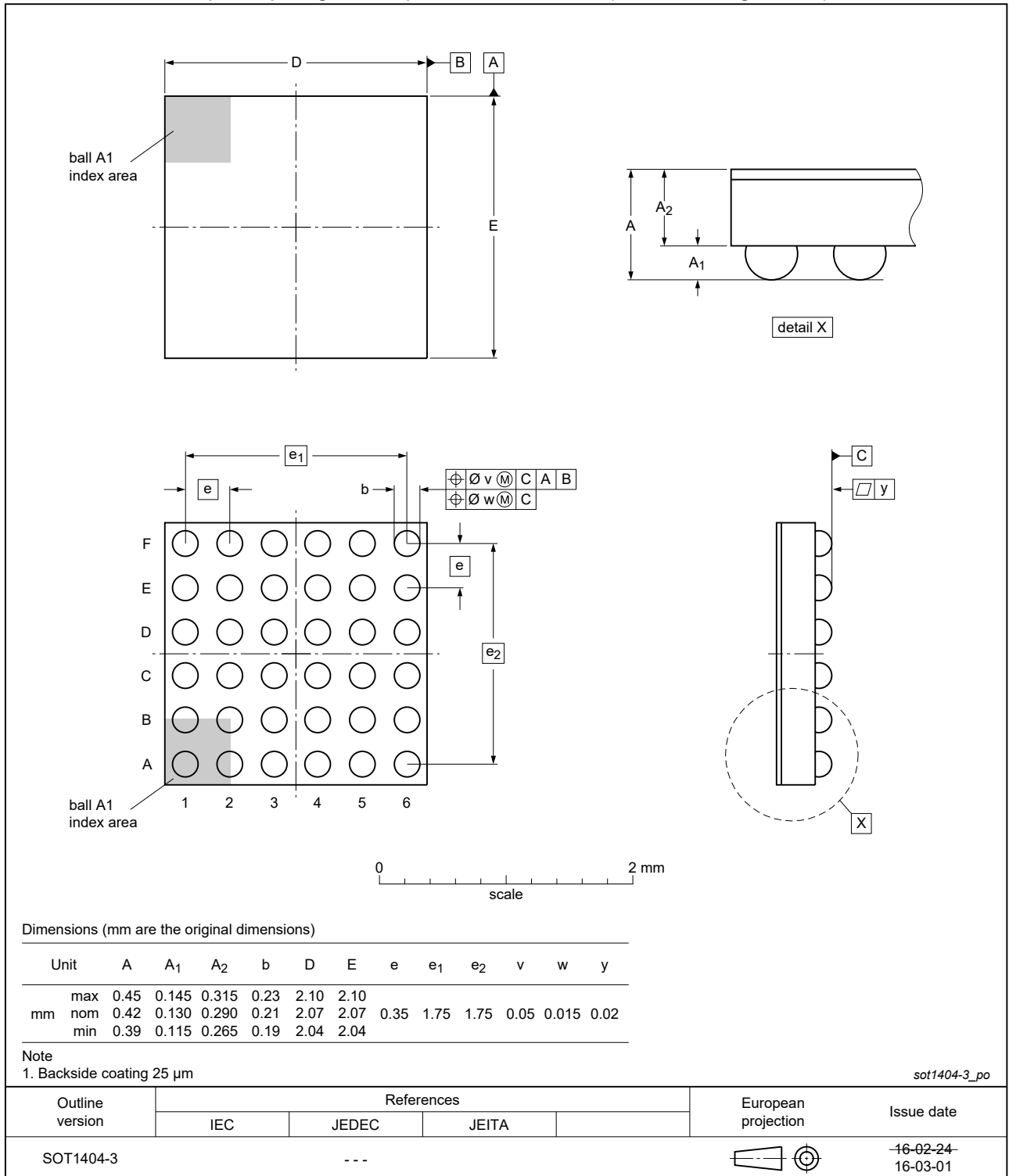


Fig. 1. Package outline WLCSP36 (SOT1404-3)

3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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